

### Product / Package Information

Package	LFCSP
Body Size (mm)	4 X 4 X .95 (2.6 EP)
Lead Count	24
Terminal Finish	100 Sn
MS Number	MS012390B

### Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	13-Mar-19

### Materials Declaration

Molding Compound							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.58E-02	84.5	845000	29.28	292774
Thermosets	Epoxy & Phenol Resin	Proprietary	2.80E-03	15.0	150000	5.20	51972
Other inorganic materials	Carbon black	1333-86-4	9.32E-05	0.5	5000	0.17	1732
Subtotal			1.86E-02	100.00	1000000	34.65	346479

Leadframe							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-02	97.50	975000	25.51	255145
Copper & its alloys	Iron	7439-89-6	3.31 E-04	2.35	23500	0.61	6150
Copper & its alloys	Zinc	7440-66-6	1.69 E-05	0.12	1200	0.03	314
Copper & its alloys	Phosphorus	7723-14-0	4.22 E-06	0.03	300	0.01	79
Subtotal			1.41 E-02	100.00	1000000	26.17	261687

Internal Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.71 E-04	100.0	1000000	1.06	10621

External Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.46 E-04	100.0	1000000	1.76	17585

Bond Wires							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.49 E-05	99.0	990000	0.12	1207
Precious Metals	Palladium	7440-05-3	6.56 E-07	1.0	10000	0.00	12
Subtotal			6.56 E-05	100.0	1000000	0.12	1219

Chip							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.11 E-03	100.0	1000000	2.07	20719

Die Attach 1							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.60 E-04	77.00	770000	0.48	4826
Other organic materials	Acrylic resin	Proprietary	2.36 E-05	7.00	70000	0.04	439
Other organic materials	Acrylate	Proprietary	1.85 E-05	5.50	55000	0.03	345
Other organic materials	Polybutadiene derivative	Proprietary	1.52 E-05	4.50	45000	0.03	282
Other organic materials	Epoxy resin	Proprietary	8.43 E-06	2.50	25000	0.02	157
Other organic materials	Butadiene Copolymer	Proprietary	5.06 E-06	1.50	15000	0.01	94
Others	Additive	Proprietary	5.06 E-06	1.50	15000	0.01	94
Others	Peroxide	Proprietary	1.69 E-06	0.50	5000	0.00	31
Subtotal			3.37 E-04	100.0	1000000	0.63	6268

Die Attach 2							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Epoxy Resin	Proprietary	1.53 E-02	85.0	850000	28.51	285109
Other organic materials	Acrylic resin	9002-84-0	2.71 E-03	15.0	150000	5.03	50313
Subtotal			1.80 E-02	100.0	1000000	33.54	335423

Package Totals				Weight (g)	Percentage (%)	PPM
				5.38 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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